



## Bond Pad Metallization Change on SLC NAND - Automotive

PCN: 33274

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**Type:** Manufacturing Process Change

**Description:** Micron will convert the bond pad metallization of Automotive SLC NAND devices at Fab 6 to align with other products at this site. Other DRAM/NAND technologies at Fab 6 use Al bond pad process and is proven to be more robust. The change will not impact the final packaged product. Micron has complete traceability via Lot ID number, Sales Order number, or Purchase Order number etc.

After the process implementation date, Micron reserves the right to ship either ALM2 or NiPd manufactured until the NiPd inventory has been depleted which is expected to last approximately six months.

Was	IS
<b>Layers:</b>	<b>Layers:</b>
Metal 2: Cu + Ni/Pd (Plating)	Metal 2: Al (Sputter)
Non-Polyimide	Polyimide

**Reason:** Improved Product Quality and Reliability, Manufacturing Efficiency

**Product Affected:** Automotive SLC NAND (M68M, M69A, M60A)

Affected Micron Part Number Component	Recommended Replacement	Customer Part Number
<b>MT29F1G08ABAEAH4-AATX:E</b>		557-1841-2-ND
<b>MT29F1G08ABAEAH4-AITX:E</b>		557-1842-2-ND
<b>MT29F1G08ABAEAWP-AATX:E</b>		557-1843-2-ND
<b>MT29F1G08ABAEAWP-AITX:E</b>		557-2000-2-ND
<b>MT29F1G08ABBEAH4-AITX:E</b>		557-1845-2-ND
<b>MT29F1G16ABBEAH4-AITX:E</b>		557-1847-2-ND
<b>MT29F2G08ABAEAH4-AATX:E</b>		557-1850-2-ND
<b>MT29F2G08ABAEAH4-AITX:E</b>		557-1851-2-ND
<b>MT29F2G08ABAEAWP-AATX:E</b>		557-1854-2-ND
<b>MT29F2G08ABAEAWP-AITX:E</b>		557-1855-2-ND
MT29F2G08ABBEAH4-AITX:E		
MT29F2G16ABAEAWP-AATX:E		
<b>MT29F2G16ABAEAWP-AITX:E</b>		557-1861-2-ND
MT29F2G16ABBEAH4-AATX:E		
<b>MT29F2G16ABBEAHC-AITX:E</b>		557-1862-2-ND
MT29F4G08ABADAH4-AATX:D		
<b>MT29F4G08ABADAH4-AITX:D</b>		557-1866-2-ND
MT29F4G08ABADAWP-AATX:D		
MT29F4G08ABADAWP-AITX:D		
<b>MT29F4G08ABBDAH4-AITX:D</b>		557-1872-2-ND
MT29F4G08ABBDAH4-AIT:D		
MT29F4G16ABADAH4-AIT:D		
MT29F8G08ADBDAH4-AAT:D		
<b>MT29F8G16ADBDAH4-AIT:D</b>		557-1884-2-ND

\*Materials that have been ordered are in bold.

<b>Method of Identification:</b>	none
<b>Micron Sites Affected:</b>	Fab 6 - US
<b>Sample Available:</b>	2019-07-31
<b>Qual Data Available:</b>	2019-05-31
<b>Product Ship Date:</b>	2020-01-31

NOTE: Per JEDEC Standard JESD46-C Section 3.2.3; lack of acknowledgment of this PCN within 30 days constitutes acceptance of change.

**Micron Confidential and Proprietary Information**

## Attachments

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There are no attachments on this PCN